

ABSTRACT OF THE DISCLOSURE

The present invention relates to the structure of the probe card. According to the present invention, the probe sections wherein the silicon probes formed 5 on the insulated circuit board are attached by the adhesive on the supporting structures; the supporting structures are supported by the fixing structures; the fixing structure is fixed on the circuit board; and the probe section's wiring and the circuit board's 10 wiring are electrically connected by the metallic wiring, the sub printed circuit and the pogo pin, or are electrically connected by the anisotropic conducting film, the sub printed circuit board and the pogo pin. In addition, a metallic layer is formed by 15 the plating of the probe in the probe section.

It reduces the manufacturing costs by enabling only the damaged probes during manufacturing to be discarded and the others to be used continually.